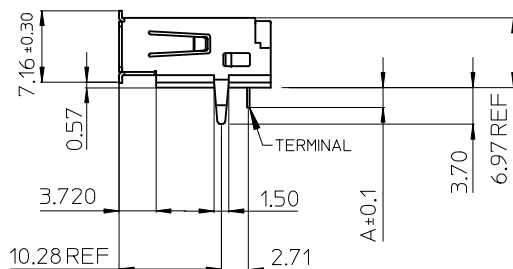
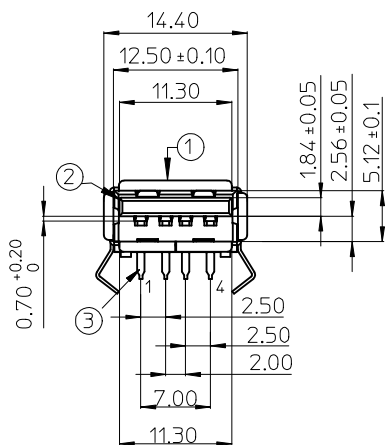
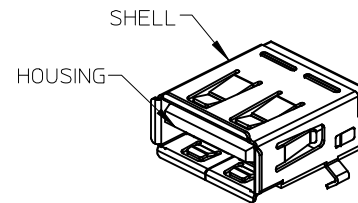


PCB LAYOUT (TOP VIEW)



NOTES:

- MATERIAL:
  - ① METAL SHELL: COPPER ALLOY.
  - ② HOUSING: SEE CHART, 30% GLASS FIBER FILLED, UL94-V0.
  - ③ TERMINAL: PHOSPHOR BRONZE
- TERMINAL:
  - CONTACT AREA: (a) GOLD FLASH.
  - (b) GOLD (Au), THICKNESS=30 MICROINCH MINIMUM.
  - SOLDER TAIL: TIN PLATED, THICKNESS=75 MICROINCH MINIMUM.
  - UNDER PLATED: NICKEL (Ni), THICKNESS=50 MICROINCH MINIMUM.
  - METAL SHELL: SEE CHART.
- RECOMMENDED PCB THICKNESS: SEE CHART
- PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002  
FOR NON IR REFER TO PS-67643-003
- TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.
- TEST SUMMARY: FOR IR REFER TO TS-67643-002  
FOR NON IR REFER TO TS-67643-003
- PACKAGE: REFER TO PK-67643-002
- LEAD FREE AND ROHS COMPLIANT PRODUCT

REVISED EC NO: D DRAWN: YPWU CHKD: APPR:	2009/08/28 DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		▽=0 ∇=0	mm    INCH	DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± ---	ANGULAR ± 3 °	CHECKED BY ALL IN	DATE 2005/03/31				
		APPROVED BY WWSCHANG	DATE 2005/03/31	MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-67643-003		SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	
67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR	
67643-1910	POLYESTER	WHITE			REFLOW PROCESS	
67643-2910	HIGH TEMPERATURE NYLON	BLACK			FOR IR	
67643-3910	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS	
67643-0911	POLYESTER	BLACK	GOLD PLATING 30 MICROINCH		NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni).	NON IR
67643-1911	POLYESTER	WHITE				REFLOW PROCESS
67643-2911	HIGH TEMPERATURE NYLON	BLACK				FOR IR
67643-3911	HIGH TEMPERATURE NYLON	WHITE				REFLOW PROCESS
PCB THICKNESS		1.60±0.05				
DIMENSION "A"		2.60				

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	
67643-0930	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH	FOR IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR	
67643-1930	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS	
67643-0931	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 30 MICROINCH			
67643-1931	HIGH TEMPERATURE NYLON	WHITE				
PCB THICKNESS		1.20±0.05				
DIMENSION "A"		2.00				

REVISED ECT NO: D DRWN:YPU CHKD: APPR:	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)			
			4 PLACES	± ---	± ---	CHECKED BY ALL IN	DATE 2005/03/31				
			3 PLACES	± ---	± ---	APPROVED BY WWSCHANG	DATE 2005/03/31	MOLEX INCORPORATED DOCUMENT NO. SD-67643-003 SHEET NO. 2 OF 2			
			2 PLACES	± 0.25	± ---	MATERIAL NO.					
1 PLACE	± 0.25	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						

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